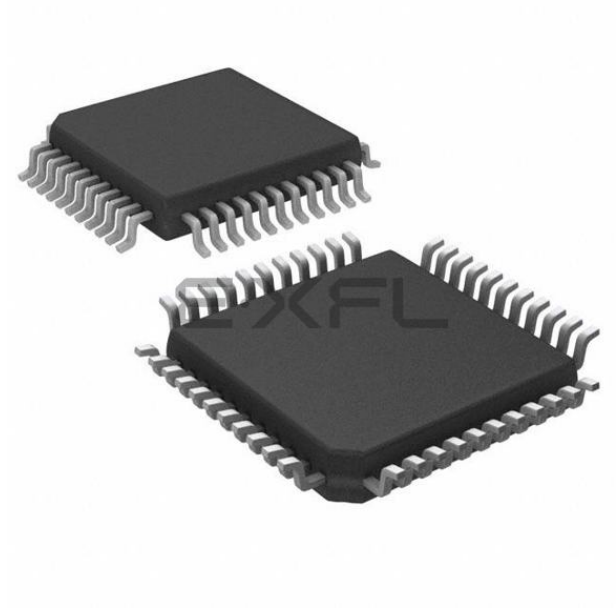

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	33MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-MQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c44-33i-pq

Table of Contents

For register and module descriptions in this data sheet, device legends show which devices apply to those sections. For example, the legend below shows that some features of only the PIC17C43, PIC17CR43, PIC17C44 are described in this section.

Applicable Devices					
42	R42	42A	43	R43	44

To Our Valued Customers

We constantly strive to improve the quality of all our products and documentation. We have spent an exceptional amount of time to ensure that these documents are correct. However, we realize that we may have missed a few things. If you find any information that is missing or appears in error from the previous version of the PIC17C4X Data Sheet (Literature Number DS30412B), please use the reader response form in the back of this data sheet to inform us. We appreciate your assistance in making this a better document.

To assist you in the use of this document, Appendix C contains a list of new information in this data sheet, while Appendix D contains information that has changed

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FIGURE 3-2: PIC17CR42/42A/43/R43/44 BLOCK DIAGRAM

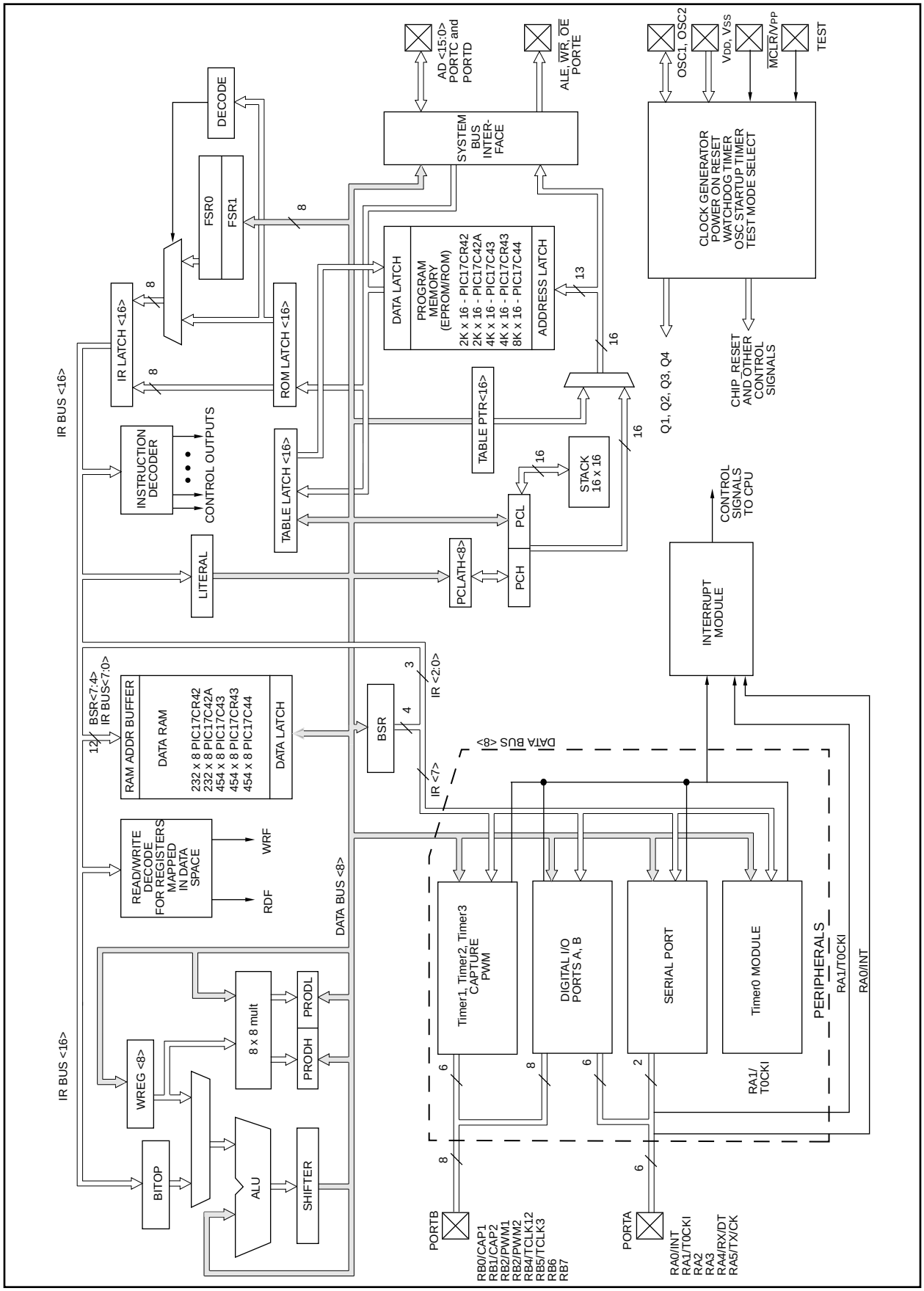
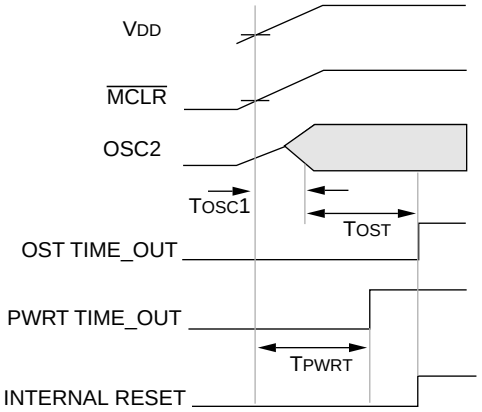


FIGURE 4-5: OSCILLATOR START-UPTIME



This figure shows in greater detail the timings involved with the oscillator start-up timer. In this example the low frequency crystal start-up time is larger than power-up time (TPWRT).
Tosc1 = time for the crystal oscillator to react to an oscillation level detectable by the Oscillator Start-up Timer (ost).
TOST = 1024TOSC.

FIGURE 4-6: USING ON-CHIP POR

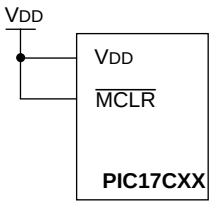
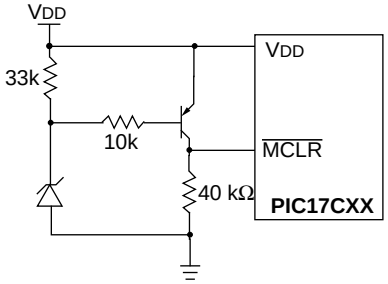
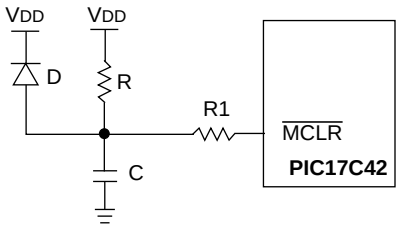


FIGURE 4-7: BROWN-OUT PROTECTION CIRCUIT 1



This circuit will activate reset when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.

FIGURE 4-8: PIC17C42 EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)

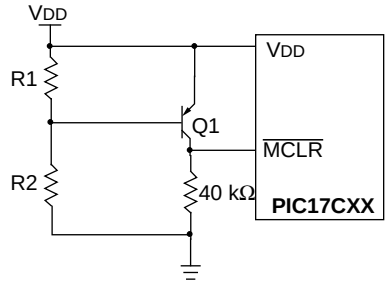


Note 1: An external Power-on Reset circuit is required only if VDD power-up time is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to ensure that the voltage drop across R does not exceed 0.2V (max. leakage current spec. on the MCLR/VPP pin is 5 μA). A larger voltage drop will degrade VIH level on the MCLR/VPP pin.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or (Electrical Overstress) EOS.

FIGURE 4-9: BROWN-OUT PROTECTION CIRCUIT 2



This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \bullet \frac{R1}{R1 + R2} = 0.7V$$

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6.0 MEMORY ORGANIZATION

There are two memory blocks in the PIC17C4X; program memory and data memory. Each block has its own bus, so that access to each block can occur during the same oscillator cycle.

The data memory can further be broken down into General Purpose RAM and the Special Function Registers (SFRs). The operation of the SFRs that control the "core" are described here. The SFRs used to control the peripheral modules are described in the section discussing each individual peripheral module.

6.1 Program Memory Organization

PIC17C4X devices have a 16-bit program counter capable of addressing a 64K x 16 program memory space. The reset vector is at 0000h and the interrupt vectors are at 0008h, 0010h, 0018h, and 0020h (Figure 6-1).

6.1.1 PROGRAM MEMORY OPERATION

The PIC17C4X can operate in one of four possible program memory configurations. The configuration is selected by two configuration bits. The possible modes are:

- Microprocessor
- Microcontroller
- Extended Microcontroller
- Protected Microcontroller

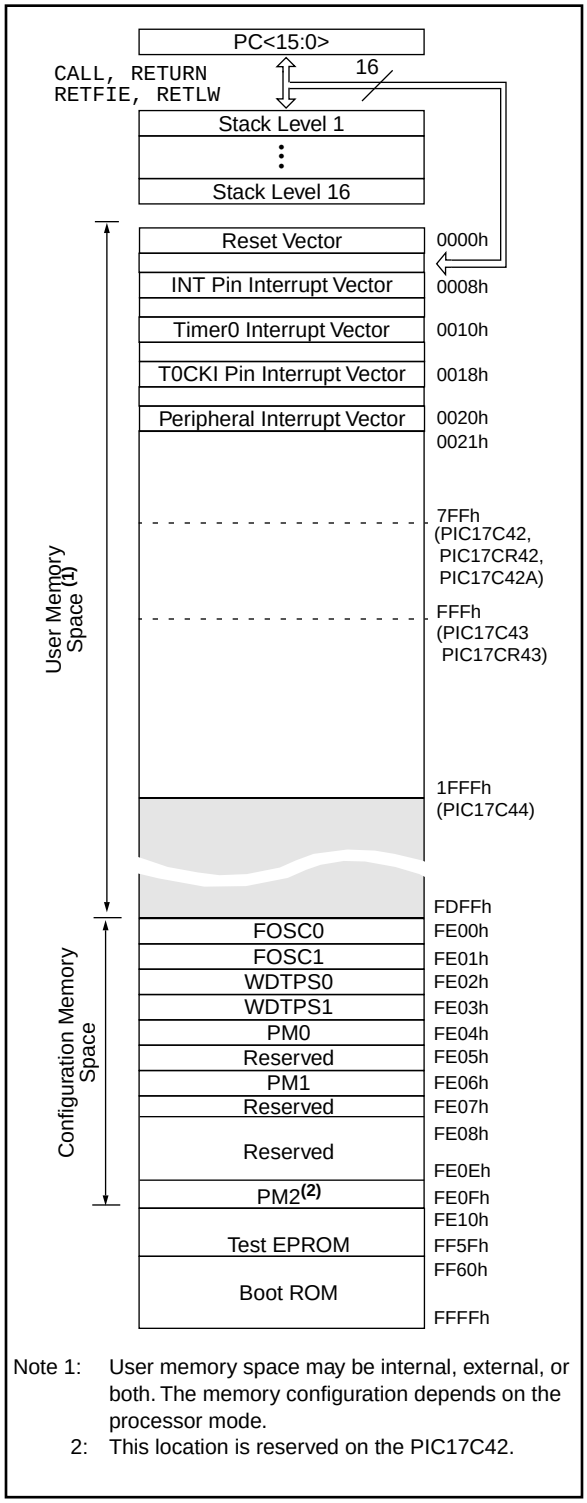
The microcontroller and protected microcontroller modes only allow internal execution. Any access beyond the program memory reads unknown data. The protected microcontroller mode also enables the code protection feature.

The extended microcontroller mode accesses both the internal program memory as well as external program memory. Execution automatically switches between internal and external memory. The 16-bits of address allow a program memory range of 64K-words.

The microprocessor mode only accesses the external program memory. The on-chip program memory is ignored. The 16-bits of address allow a program memory range of 64K-words. Microprocessor mode is the default mode of an unprogrammed device.

The different modes allow different access to the configuration bits, test memory, and boot ROM. Table 6-1 lists which modes can access which areas in memory. Test Memory and Boot Memory are not required for normal operation of the device. Care should be taken to ensure that no unintended branches occur to these areas.

FIGURE 6-1: PROGRAM MEMORY MAP AND STACK



Note 1: User memory space may be internal, external, or both. The memory configuration depends on the processor mode.
2: This location is reserved on the PIC17C42.

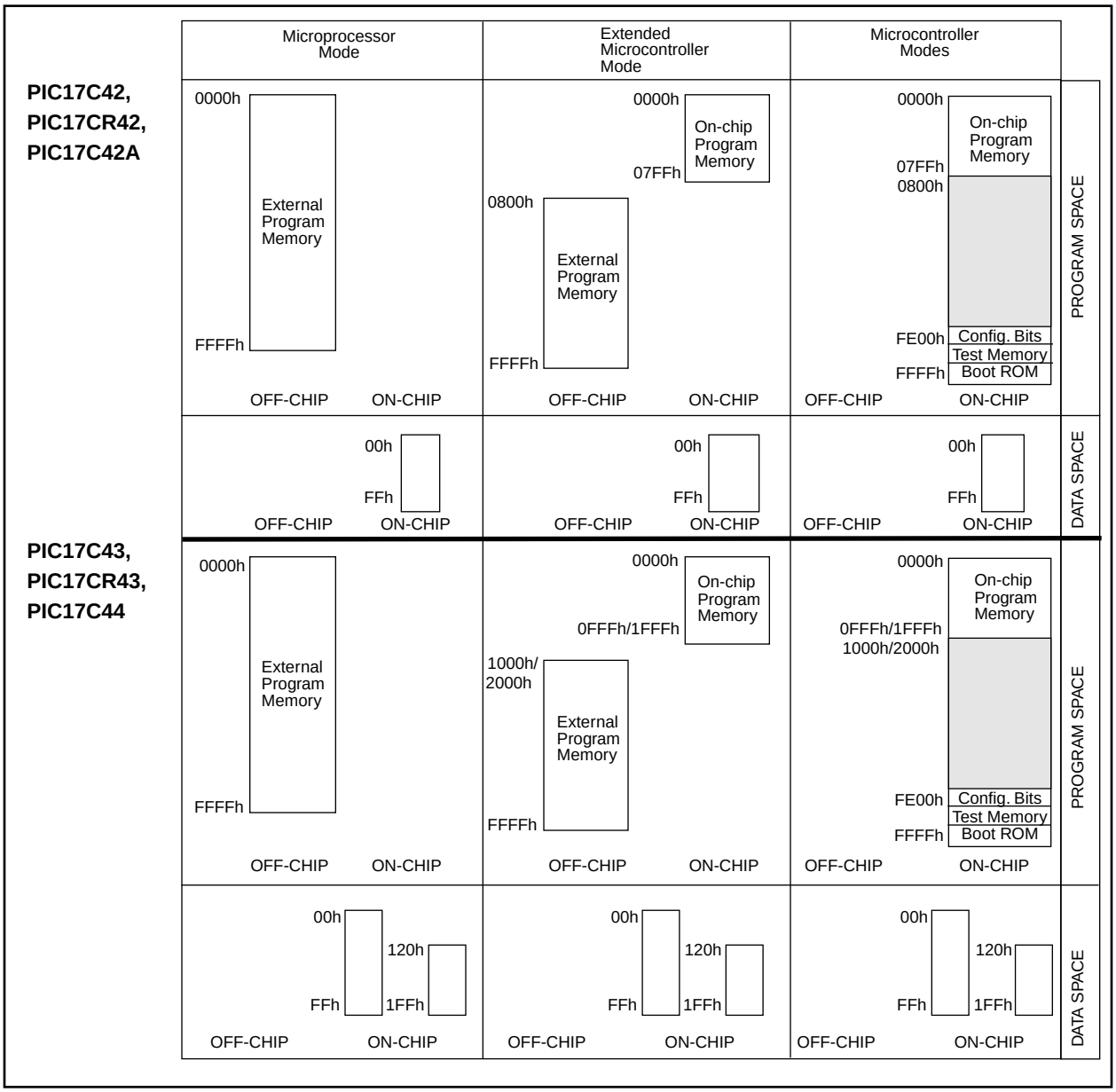
TABLE 6-1: MODE MEMORY ACCESS

Operating Mode	Internal Program Memory	Configuration Bits, Test Memory, Boot ROM
Microprocessor	No Access	No Access
Microcontroller	Access	Access
Extended Microcontroller	Access	No Access
Protected Microcontroller	Access	Access

The PIC17C4X can operate in modes where the program memory is off-chip. They are the microprocessor and extended microcontroller modes. The microprocessor mode is the default for an unprogrammed device.

Regardless of the processor mode, data memory is always on-chip.

FIGURE 6-2: MEMORY MAP IN DIFFERENT MODES



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6.4.1 INDIRECT ADDRESSING REGISTERS

The PIC17C4X has four registers for indirect addressing. These registers are:

- INDF0 and FSR0
- INDF1 and FSR1

Registers INDF0 and INDF1 are not physically implemented. Reading or writing to these registers activates indirect addressing, with the value in the corresponding FSR register being the address of the data. The FSR is an 8-bit register and allows addressing anywhere in the 256-byte data memory address range. For banked memory, the bank of memory accessed is specified by the value in the BSR.

If file INDF0 (or INDF1) itself is read indirectly via an FSR, all '0's are read (Zero bit is set). Similarly, if INDF0 (or INDF1) is written to indirectly, the operation will be equivalent to a NOP, and the status bits are not affected.

6.4.2 INDIRECT ADDRESSING OPERATION

The indirect addressing capability has been enhanced over that of the PIC16CXX family. There are two control bits associated with each FSR register. These two bits configure the FSR register to:

- Auto-decrement the value (address) in the FSR after an indirect access
- Auto-increment the value (address) in the FSR after an indirect access
- No change to the value (address) in the FSR after an indirect access

These control bits are located in the ALUSTA register. The FSR1 register is controlled by the FS3:FS2 bits and FSR0 is controlled by the FS1:FS0 bits.

When using the auto-increment or auto-decrement features, the effect on the FSR is not reflected in the ALUSTA register. For example, if the indirect address causes the FSR to equal '0', the Z bit will not be set.

If the FSR register contains a value of 0h, an indirect read will read 0h (Zero bit is set) while an indirect write will be equivalent to a NOP (status bits are not affected).

Indirect addressing allows single cycle data transfers within the entire data space. This is possible with the use of the MOVPF and MOVFP instructions, where either 'p' or 'f' is specified as INDF0 (or INDF1).

If the source or destination of the indirect address is in banked memory, the location accessed will be determined by the value in the BSR.

A simple program to clear RAM from 20h - FFh is shown in Example 6-1.

EXAMPLE 6-1: INDIRECT ADDRESSING

```
    MOVLW    0x20          ;
    MOVWF    FSR0          ; FSR0 = 20h
    BCF      ALUSTA, FS1   ; Increment FSR
    BSF      ALUSTA, FS0   ; after access
    BCF      ALUSTA, C     ; C = 0
    MOVLW    END_RAM + 1   ;
LP  CLRF     INDF0         ; Addr(FSR) = 0
    CPFSEQ   FSR0          ; FSR0 = END_RAM+1?
    GOTO     LP            ; NO, clear next
    :                      ; YES, All RAM is
    :                      ; cleared
```

6.5 Table Pointer (TBLPTRL and TBLPTRH)

File registers TBLPTRL and TBLPTRH form a 16-bit pointer to address the 64K program memory space. The table pointer is used by instructions TABLWT and TABLRD.

The TABLRD and the TABLWT instructions allow transfer of data between program and data space. The table pointer serves as the 16-bit address of the data word within the program memory. For a more complete description of these registers and the operation of Table Reads and Table Writes, see Section 7.0.

6.6 Table Latch (TBLATH, TBLATL)

The table latch (TBLAT) is a 16-bit register, with TBLATH and TBLATL referring to the high and low bytes of the register. It is not mapped into data or program memory. The table latch is used as a temporary holding latch during data transfer between program and data memory (see descriptions of instructions TABLRD, TABLWT, TLRD and TLWT). For a more complete description of these registers and the operation of Table Reads and Table Writes, see Section 7.0.

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7.3 Table Reads

The table read allows the program memory to be read. This allows constant data to be stored in the program memory space, and retrieved into data memory when needed. Example 7-2 reads the 16-bit value at program memory address TBLPTR. After the dummy byte has been read from the TABLATH, the TABLATH is loaded with the 16-bit data from program memory address TBLPTR + 1. The first read loads the data into the latch, and can be considered a dummy read (unknown data loaded into 'f'). INDF0 should be configured for either auto-increment or auto-decrement.

EXAMPLE 7-2: TABLE READ

```
MOVLW   HIGH (TBL_ADDR) ; Load the Table
MOVWF   TBLPTRH         ;   address
MOVLW   LOW (TBL_ADDR)  ;
MOVWF   TBLPTRL         ;
TABLRD  0,0,DUMMY       ; Dummy read,
                        ;  Updates TABLATCH
TLRD    1, INDF0        ; Read HI byte
                        ;   of TABLATCH
TABLRD  0,1,INDF0       ; Read LO byte
                        ;   of TABLATCH and
                        ;   Update TABLATCH
```

FIGURE 7-7: TABLRD TIMING

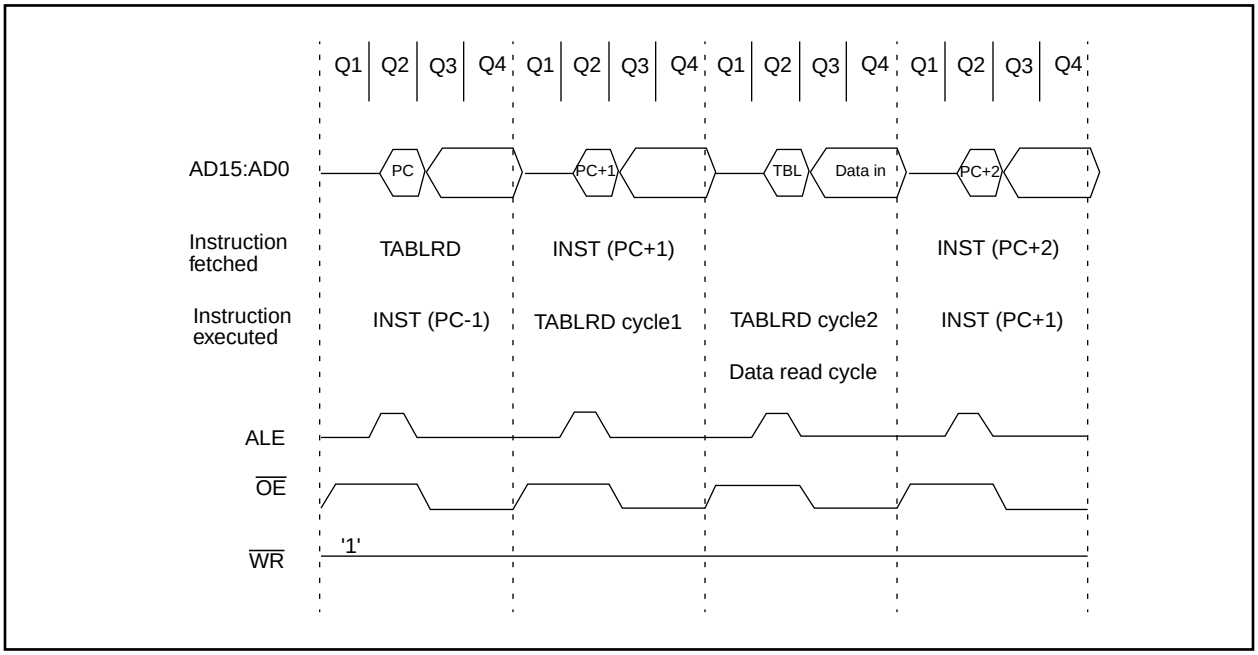
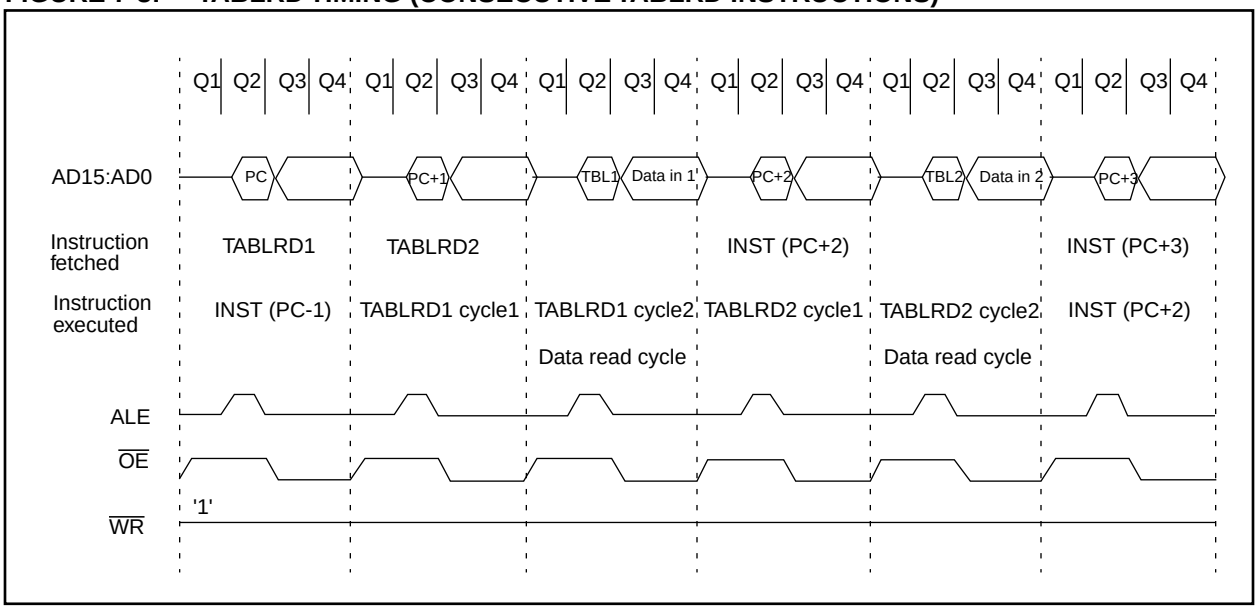


FIGURE 7-8: TABLRD TIMING (CONSECUTIVE TABLRD INSTRUCTIONS)



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12.1.3.1 PWM PERIODS

The period of the PWM1 output is determined by Timer1 and its period register (PR1). The period of the PWM2 output can be software configured to use either Timer1 or Timer2 as the time-base. When TM2PW2 bit (PW2DCL<5>) is clear, the time-base is determined by TMR1 and PR1. When TM2PW2 is set, the time-base is determined by Timer2 and PR2.

Running two different PWM outputs on two different timers allows different PWM periods. Running both PWMs from Timer1 allows the best use of resources by freeing Timer2 to operate as an 8-bit timer. Timer1 and Timer2 can not be used as a 16-bit timer if either PWM is being used.

The PWM periods can be calculated as follows:

period of PWM1 =[(PR1) + 1] x 4TOSC

period of PWM2 =[(PR1) + 1] x 4TOSC or
[(PR2) + 1] x 4TOSC

The duty cycle of PWMx is determined by the 10-bit value DCx<9:0>. The upper 8-bits are from register PWxDCH and the lower 2-bits are from PWxDCL<7:6> (PWxDCH:PWxDCL<7:6>). Table 12-3 shows the maximum PWM frequency (FPWM) given the value in the period register.

The number of bits of resolution that the PWM can achieve depends on the operation frequency of the device as well as the PWM frequency (FPWM).

Maximum PWM resolution (bits) for a given PWM frequency:

$$= \frac{\log\left(\frac{FOSC}{FPWM}\right)}{\log(2)} \text{ bits}$$

The PWMx duty cycle is as follows:

PWMx Duty Cycle = (DCx) x TOSC

where DCx represents the 10-bit value from PWxDCH:PWxDCL.

If DCx = 0, then the duty cycle is zero. If PRx = PWxDCH, then the PWM output will be low for one to four Q-clock (depending on the state of the PWxDCL<7:6> bits). For a Duty Cycle to be 100%, the PWxDCH value must be greater then the PRx value.

The duty cycle registers for both PWM outputs are double buffered. When the user writes to these registers, they are stored in master latches. When TMR1 (or TMR2) overflows and a new PWM period begins, the master latch values are transferred to the slave latches and the PWMx pin is forced high.

Note:	For PW1DCH, PW1DCL, PW2DCH and PW2DCL registers, a write operation writes to the "master latches" while a read operation reads the "slave latches". As a result, the user may not read back what was just written to the duty cycle registers.

The user should also avoid any "read-modify-write" operations on the duty cycle registers, such as: ADDWF PW1DCH. This may cause duty cycle outputs that are unpredictable.

TABLE 12-3: PWM FREQUENCY vs. RESOLUTION AT 25 MHz

PWM Frequency	Frequency (kHz)				
	24.4	**48.8**	**65.104**	**97.66**	**390.6**
PRx Value	0xFF	0x7F	0x5F	0x3F	0x0F
High Resolution	10-bit	9-bit	8.5-bit	8-bit	6-bit
Standard Resolution	8-bit	7-bit	6.5-bit	6-bit	4-bit

12.1.3.2 PWM INTERRUPTS

The PWM module makes use of TMR1 or TMR2 interrupts. A timer interrupt is generated when TMR1 or TMR2 equals its period register and is cleared to zero. This interrupt also marks the beginning of a PWM cycle. The user can write new duty cycle values before the timer roll-over. The TMR1 interrupt is latched into the TMR1IF bit and the TMR2 interrupt is latched into the TMR2IF bit. These flags must be cleared in software.

12.1.3.3 EXTERNAL CLOCK SOURCE

The PWMs will operate regardless of the clock source of the timer. The use of an external clock has ramifications that must be understood. Because the external TCLK12 input is synchronized internally (sampled once per instruction cycle), the time TCLK12 changes to the time the timer increments will vary by as much as TCY (one instruction cycle). This will cause jitter in the duty cycle as well as the period of the PWM output.

This jitter will be ±TCY, unless the external clock is synchronized with the processor clock. Use of one of the PWM outputs as the clock source to the TCLKx input, will supply a synchronized clock.

In general, when using an external clock source for PWM, its frequency should be much less than the device frequency (Fosc).

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13.3.2 USART SYNCHRONOUS MASTER RECEPTION

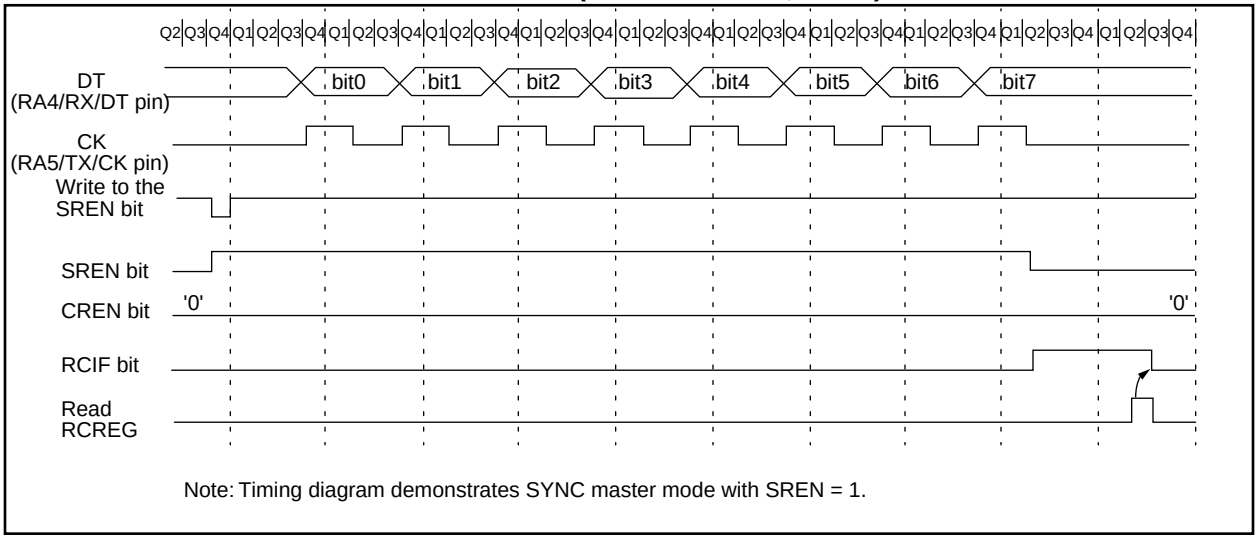
Once synchronous mode is selected, reception is enabled by setting either the SREN (RCSTA<5>) bit or the CREN (RCSTA<4>) bit. Data is sampled on the RA4/RX/DT pin on the falling edge of the clock. If SREN is set, then only a single word is received. If CREN is set, the reception is continuous until CREN is reset. If both bits are set, then CREN takes precedence. After clocking the last bit, the received data in the Receive Shift Register (RSR) is transferred to RCREG (if it is empty). If the transfer is complete, the interrupt bit RCIF (PIR<0>) is set. The actual interrupt can be enabled/disabled by setting/clearing the RCIE (PIE<0>) bit. RCIF is a read only bit which is RESET by the hardware. In this case it is reset when RCREG has been read and is empty. RCREG is a double buffered register; i.e., it is a two deep FIFO. It is possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte to begin shifting into the RSR. On the clocking of the last bit of the third byte, if RCREG is still full, then the overrun error bit OERR (RCSTA<1>) is set. The word in the RSR will be lost. RCREG can be read twice to retrieve the two bytes in the FIFO. The OERR bit has to be cleared in software. This is done by clearing the CREN bit. If OERR bit is set, transfers from RSR to RCREG are inhibited, so it is essential to clear OERR bit if it is set. The 9th receive bit is buffered the same way as the receive data. Reading the RCREG register will allow the RX9D and FERR bits to be loaded with values for the next received data; therefore, it is essential for the user to read the RCSTA register before reading RCREG in order not to lose the old FERR and RX9D information.

Steps to follow when setting up a Synchronous Master Reception:

1. Initialize the SPBRG register for the appropriate baud rate. See Section 13.1 for details.
2. Enable the synchronous master serial port by setting bits SYNC, SPEN, and CSRC.
3. If interrupts are desired, then set the RCIE bit.
4. If 9-bit reception is desired, then set the RX9 bit.
5. If a single reception is required, set bit SREN. For continuous reception set bit CREN.
6. The RCIF bit will be set when reception is complete and an interrupt will be generated if the RCIE bit was set.
7. Read RCSTA to get the ninth bit (if enabled) and determine if any error occurred during reception.
8. Read the 8-bit received data by reading RCREG.
9. If any error occurred, clear the error by clearing CREN.

Note:	To terminate a reception, either clear the SREN and CREN bits, or the SPEN bit. This will reset the receive logic, so that it will be in the proper state when receive is re-enabled.

FIGURE 13-11: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note: Timing diagram demonstrates SYNC master mode with SREN = 1.

FIGURE 14-3: CRYSTAL OPERATION, OVERTONE CRYSTALS (XT OSC CONFIGURATION)

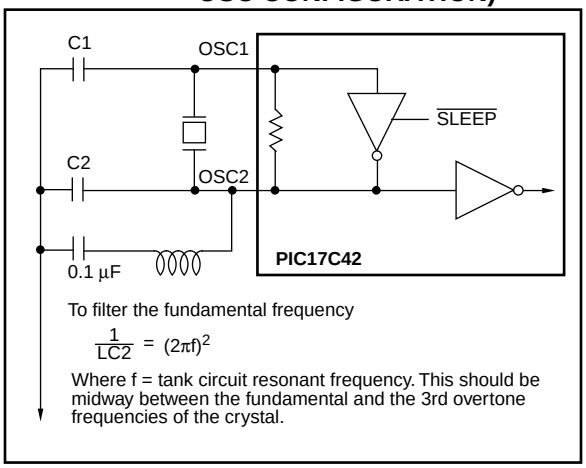


TABLE 14-2: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Oscillator Type	Resonator Frequency	Capacitor Range C1 = C2
LF	455 kHz 2.0 MHz	15 - 68 pF 10 - 33 pF
XT	4.0 MHz 8.0 MHz 16.0 MHz	22 - 68 pF 33 - 100 pF 33 - 100 pF
Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.		
Resonators Used:		
455 kHz	Panasonic EFO-A455K04B	± 0.3%
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%
Resonators used did not have built-in capacitors.		

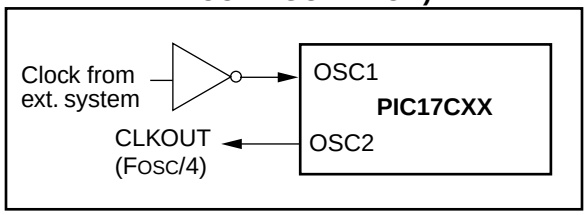
TABLE 14-3: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Freq	C1	C2
LF	32 kHz(1) 1 MHz 2 MHz	100-150 pF 10-33 pF 10-33 pF	100-150 pF 10-33 pF 10-33 pF
XT	2 MHz 4 MHz 8 MHz (2) 16 MHz 25 MHz 32 MHz (3)	47-100 pF 15-68 pF 15-47 pF TBD 15-47 pF 0 (3)	47-100 pF 15-68 pF 15-47 pF TBD 15-47 pF 0 (3)
Higher capacitance increases the stability of the oscillator but also increases the start-up time and the oscillator current. These values are for design guidance only. RS may be required in XT mode to avoid overdriving the crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values for external components. Note 1: For VDD > 4.5V, C1 = C2 ≈ 30 pF is recommended. 2: RS of 330Ω is required for a capacitor combination of 15/15 pF. 3: Only the capacitance of the board was present.			
Crystals Used:			
32.768 kHz	Epson C-001R32.768K-A	± 20 PPM	
1.0 MHz	ECS-10-13-1	± 50 PPM	
2.0 MHz	ECS-20-20-1	± 50 PPM	
4.0 MHz	ECS-40-20-1	± 50 PPM	
8.0 MHz	ECS ECS-80-S-4 ECS-80-18-1	± 50 PPM	
16.0 MHz	ECS-160-20-1	TBD	
25 MHz	CTS CTS25M	± 50 PPM	
32 MHz	CRYSTEK HF-2	± 50 PPM	

14.2.3 EXTERNAL CLOCK OSCILLATOR

In the EC oscillator mode, the OSC1 input can be driven by CMOS drivers. In this mode, the OSC1/CLKIN pin is hi-impedance and the OSC2/CLKOUT pin is the CLKOUT output (4 TOSC).

FIGURE 14-4: EXTERNAL CLOCK INPUT OPERATION (EC OSC CONFIGURATION)



15.0 INSTRUCTION SET SUMMARY

The PIC17CXX instruction set consists of 58 instructions. Each instruction is a 16-bit word divided into an OPCODE and one or more operands. The opcode specifies the instruction type, while the operand(s) further specify the operation of the instruction. The PIC17CXX instruction set can be grouped into three types:

- byte-oriented
- bit-oriented
- literal and control operations.

These formats are shown in Figure 15-1.

Table 15-1 shows the field descriptions for the opcodes. These descriptions are useful for understanding the opcodes in Table 15-2 and in each specific instruction descriptions.

byte-oriented instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' = '0', the result is placed in the WREG register. If 'd' = '1', the result is placed in the file register specified by the instruction.

bit-oriented instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

literal and control operations, 'k' represents an 8- or 11-bit constant or literal value.

The instruction set is highly orthogonal and is grouped into:

- byte-oriented operations
- bit-oriented operations
- literal and control operations

All instructions are executed within one single instruction cycle, unless:

- a conditional test is true
- the program counter is changed as a result of an instruction
- a table read or a table write instruction is executed (in this case, the execution takes two instruction cycles with the second cycle executed as a NOP)

One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 25 MHz, the normal instruction execution time is 160 ns. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 320 ns.

TABLE 15-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (00h to FFh)
p	Peripheral register file address (00h to 1Fh)
i	Table pointer control i = '0' (do not change) i = '1' (increment after instruction execution)
t	Table byte select t = '0' (perform operation on lower byte) t = '1' (perform operation on upper byte literal field, constant data)
WREG	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= '0' or '1') The assembler will generate code with x = '0'. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select 0 = store result in WREG 1 = store result in file register f Default is d = '1'
u	Unused, encoded as '0'
s	Destination select 0 = store result in file register f and in the WREG 1 = store result in file register f Default is s = '1'
label	Label name
C,DC,Z,OV	ALU status bits Carry, Digit Carry, Zero, Overflow
GLINTD	Global Interrupt Disable bit (CPUSTA<4>)
TBLPTR	Table Pointer (16-bit)
TBLAT	Table Latch (16-bit) consists of high byte (TBLATH) and low byte (TBLATL)
TBLATL	Table Latch low byte
TBLATH	Table Latch high byte
TOS	Top of Stack
PC	Program Counter
BSR	Bank Select Register
WDT	Watchdog Timer Counter
$\overline{TO}$	Time-out bit
$\overline{PD}$	Power-down bit
dest	Destination either the WREG register or the specified register file location
[ ]	Options
( )	Contents
$\rightarrow$	Assigned to
< >	Register bit field
$\in$	In the set of
italics	User defined term (font is courier)

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CPFSEQ **Compare f with WREG, skip if f = WREG**

Syntax: [*label*] CPFSEQ f

Operands: $0 \le f \le 255$

Operation: (f) – (WREG), skip if (f) = (WREG) (unsigned comparison)

Status Affected: None

Encoding:

0011	0001	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of WREG by performing an unsigned subtraction.

If 'f' = WREG then the fetched instruction is discarded and an NOP is executed instead making this a two-cycle instruction.

Words: 1

Cycles: 1 (2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	NOP

If skip:

Q1	Q2	Q3	Q4
Forced NOP	NOP	Execute	NOP

Example:

```
HERE    CPFSEQ REG
NEQUAL  :
EQUAL   :
```

Before Instruction
PC Address = HERE
WREG = ?
REG = ?

After Instruction
If REG = WREG;
PC = Address (EQUAL)
If REG ≠ WREG;
PC = Address (NEQUAL)

CPFSGT **Compare f with WREG, skip if f > WREG**

Syntax: [*label*] CPFSGT f

Operands: $0 \le f \le 255$

Operation: (f) – (WREG), skip if (f) > (WREG) (unsigned comparison)

Status Affected: None

Encoding:

0011	0010	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of the WREG by performing an unsigned subtraction.

If the contents of 'f' > the contents of WREG then the fetched instruction is discarded and an NOP is executed instead making this a two-cycle instruction.

Words: 1

Cycles: 1 (2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	NOP

If skip:

Q1	Q2	Q3	Q4
Forced NOP	NOP	Execute	NOP

Example:

```
HERE     CPFSGT REG
NGREATER :
GREATER  :
```

Before Instruction
PC = Address (HERE)
WREG = ?

After Instruction
If REG > WREG;
PC = Address (GREATER)
If REG ≤ WREG;
PC = Address (NGREATER)

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NOTES:

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Applicable Devices	42	R42	42A	43	R43	44

17.1 DC CHARACTERISTICS: PIC17C42-16 (Commercial, Industrial) PIC17C42-25 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	4.5	–	5.5	V	
D002	VDR	RAM Data Retention Voltage (Note 1)	1.5 *	–	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure internal Power-on Reset signal	–	VSS	–	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure internal Power-on Reset signal	0.060*	–	–	mV/ms	See section on Power-on Reset for details
D010	IDD	Supply Current (Note 2)	–	3	6	mA	FOSC = 4 MHz (Note 4)
D011			–	6	12 *	mA	FOSC = 8 MHz
D012			–	11	24 *	mA	FOSC = 16 MHz
D013			–	19	38	mA	FOSC = 25 MHz
D014			–	95	150	µA	FOSC = 32 kHz WDT enabled (EC osc configuration)
D020	IPD	Power-down Current (Note 3)	–	10	40	µA	VDD = 5.5V, WDT enabled
D021			–	< 1	5	µA	VDD = 5.5V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD or VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.
Current consumed from the oscillator and I/O's driving external capacitive or resistive loads need to be considered.
For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD / (2 • R).
For capacitive loads, The current can be estimated (for an individual I/O pin) as (CL • VDD) • f
CL = Total capacitive load on the I/O pin; f = average frequency on the I/O pin switches.
The capacitive currents are most significant when the device is configured for external execution (includes extended microcontroller mode).

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula IR = VDD/2Rext (mA) with Rext in kOhm.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 18-5: TRANSCONDUCTANCE (gm) OF LF OSCILLATOR vs. VDD

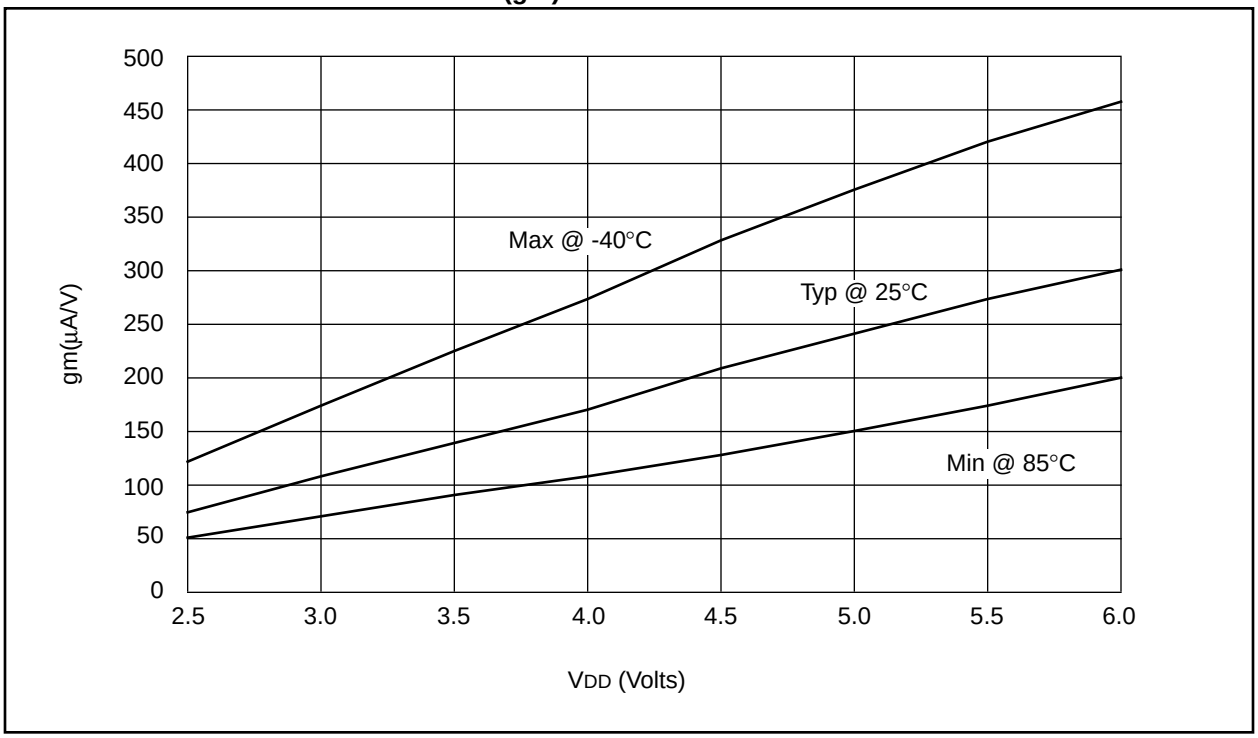
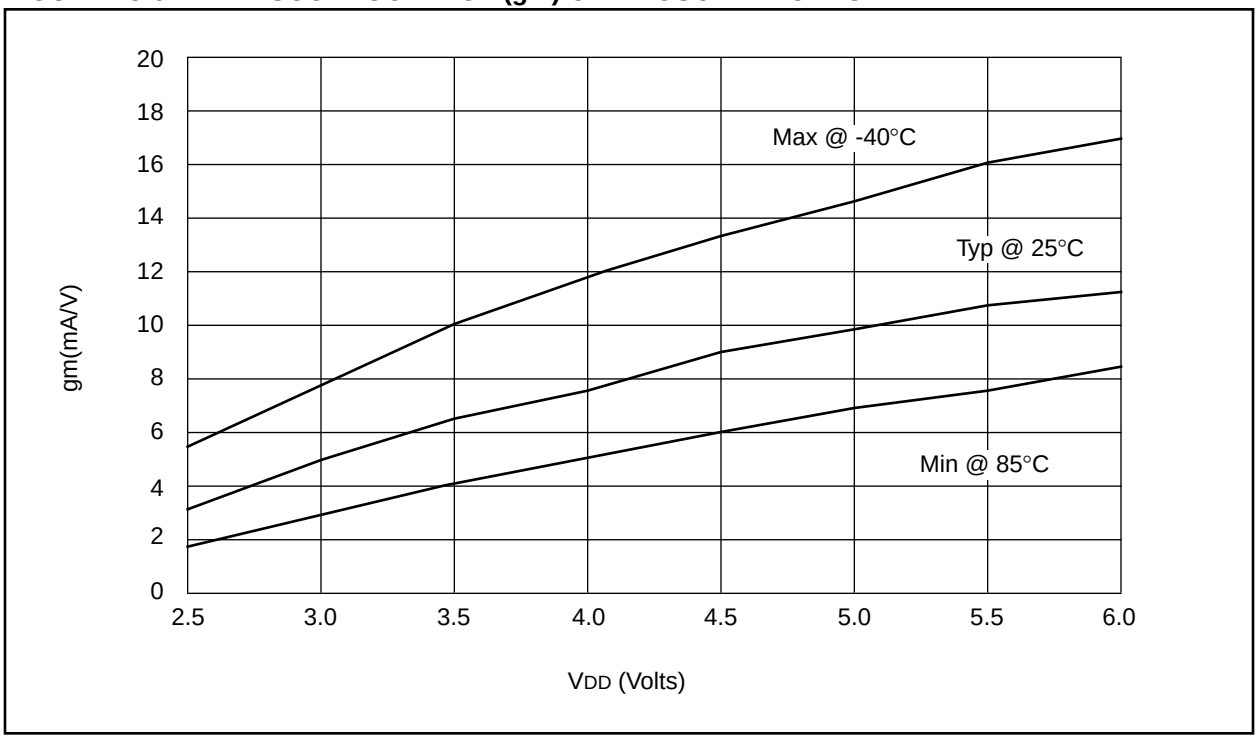


FIGURE 18-6: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



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Applicable Devices	42	R42	42A	43	R43	44

FIGURE 19-11: MEMORY INTERFACE WRITE TIMING (NOT SUPPORTED IN PIC17LC4X DEVICES)

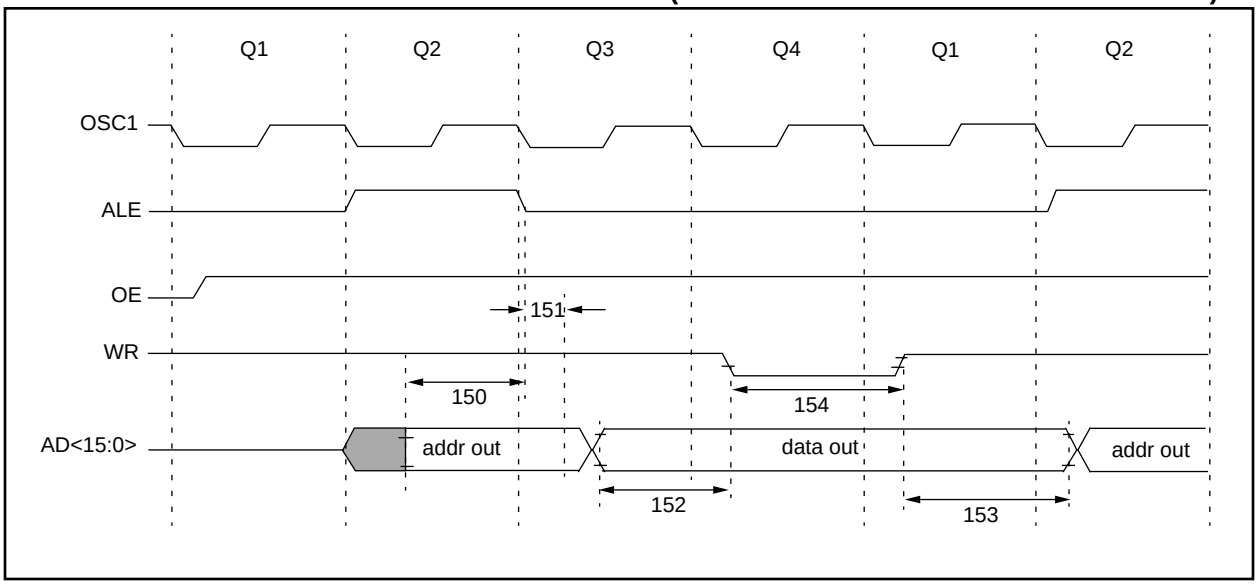

TABLE 19-11: MEMORY INTERFACE WRITE REQUIREMENTS (NOT SUPPORTED IN PIC17LC4X DEVICES)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
150	TadV2alL	AD<15:0> (address) valid to ALE↓ (address setup time)	0.25Tcy - 10	—	—	ns	
151	TalL2adI	ALE↓ to address out invalid (address hold time)	0	—	—	ns	
152	TadV2wrL	Data out valid to $\overline{WR}$↓ (data setup time)	0.25Tcy - 40	—	—	ns	
153	TwrH2adI	$\overline{WR}$↑ to data out invalid (data hold time)	—	0.25TCY §	—	ns	
154	TwrL	$\overline{WR}$ pulse width	—	0.25TCY §	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

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Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-5: TRANSCONDUCTANCE (gm) OF LF OSCILLATOR vs. VDD

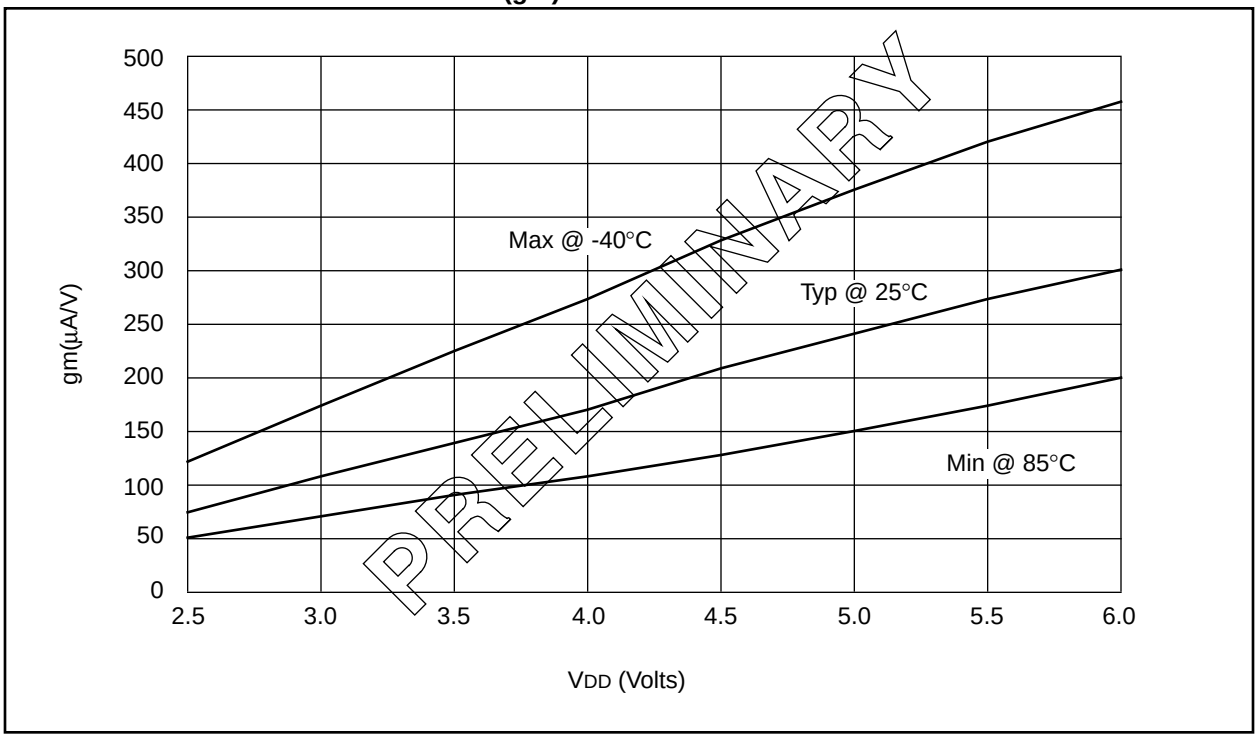
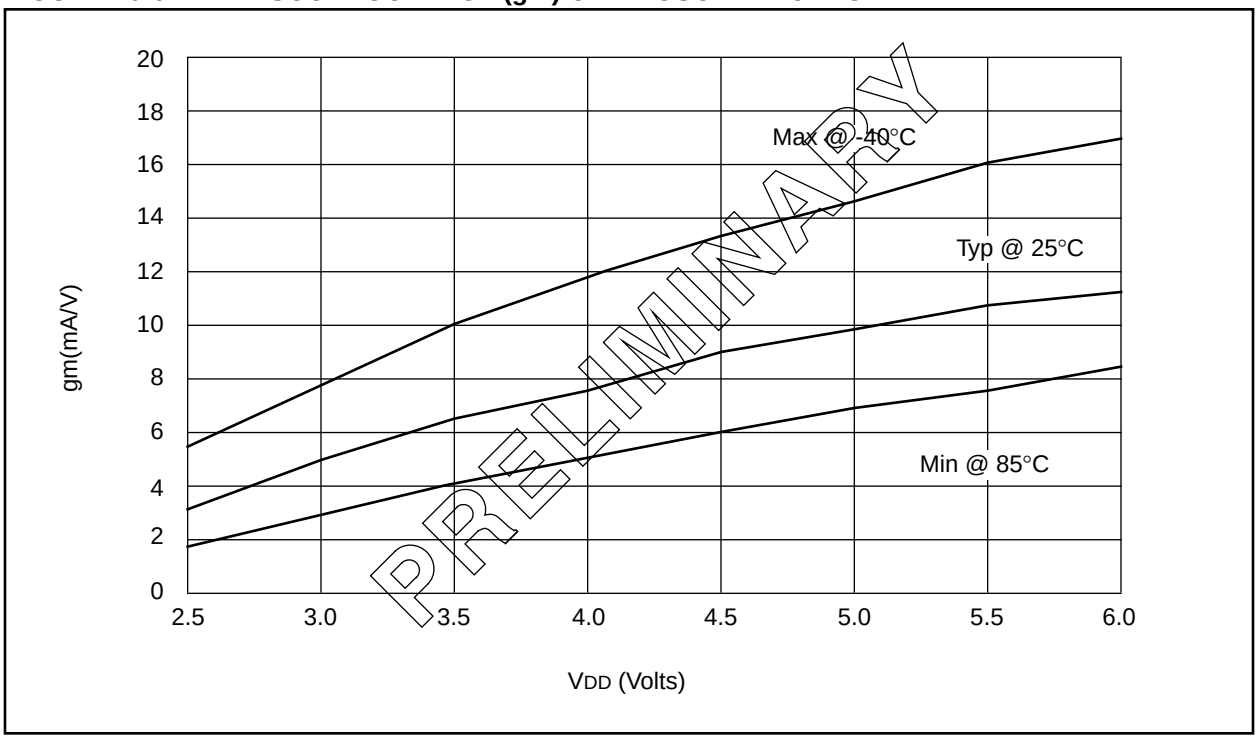


FIGURE 20-6: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



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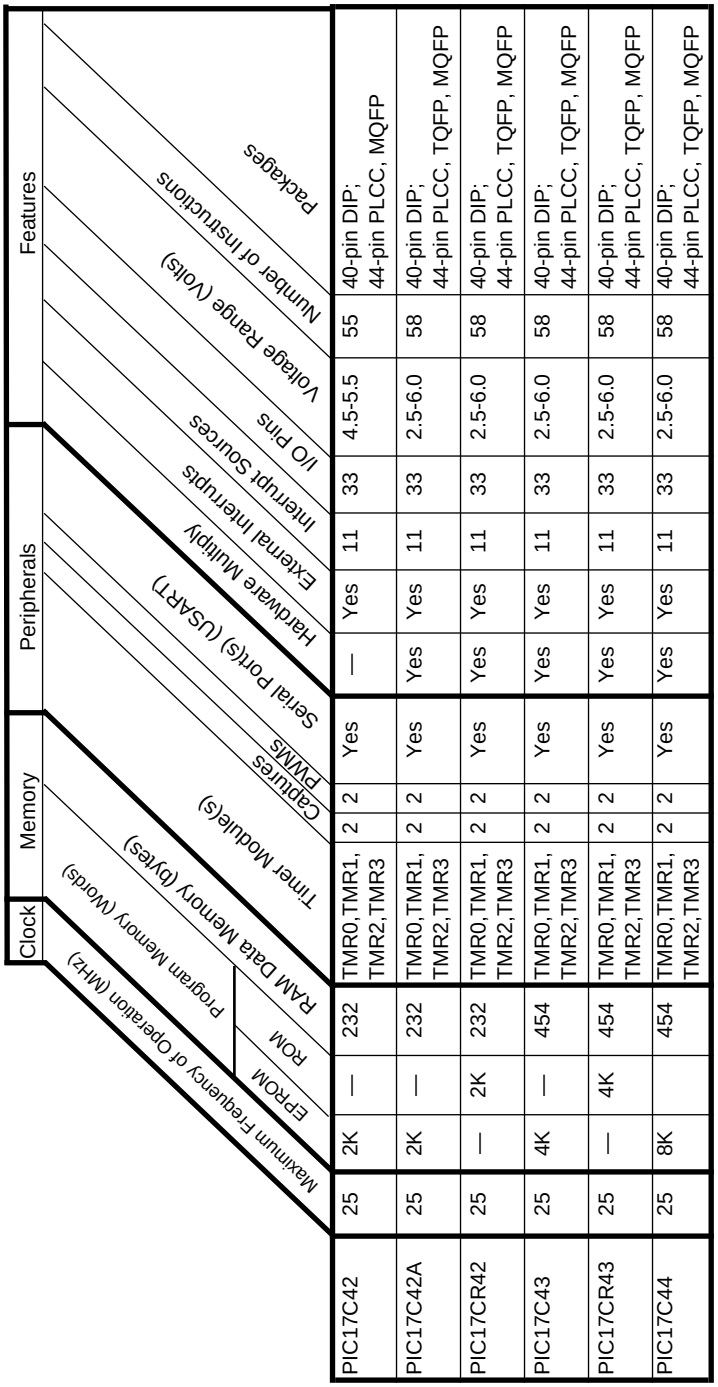
E.3 PIC16CXXX Family of Devices

	Clock	Memory			Peripherals				Features		
	Maximum Frequency of Operation (MHz)	EPROM	Program Memory (x14 words)	Data Memory (bytes)	Timer Module(s)	Comparator(s)	Internal Reference Voltage	Interrupt Sources	I/O Pins	Voltage Range (Volts)	Brown-out Reset	Packages
PIC16C554	20	512	80	TMR0	—	—		3	13	2.5-6.0	—	18-pin DIP, SOIC; 20-pin SSOP
PIC16C556	20	1K	80	TMR0	—	—		3	13	2.5-6.0	—	18-pin DIP, SOIC; 20-pin SSOP
PIC16C558	20	2K	128	TMR0	—	—		3	13	2.5-6.0	—	18-pin DIP, SOIC; 20-pin SSOP
PIC16C620	20	512	80	TMR0	2	Yes		4	13	2.5-6.0	Yes	18-pin DIP, SOIC; 20-pin SSOP
PIC16C621	20	1K	80	TMR0	2	Yes		4	13	2.5-6.0	Yes	18-pin DIP, SOIC; 20-pin SSOP
PIC16C622	20	2K	128	TMR0	2	Yes		4	13	2.5-6.0	Yes	18-pin DIP, SOIC; 20-pin SSOP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.
All PIC16C6XXX Family devices use serial programming with clock pin RB6 and data pin RB7.

E.8 PIC17CXX Family of Devices



	Clock	Memory					Peripherals					Features		
	Maximum Frequency of Operation (MHz)	EPROM	ROM	RAM Data Memory (bytes)	Program Memory (Words)	Timer Module(s)	Captures PWMs	Serial Port(s) (USART)	Hardware Multiply	External Interrupts	Interrupt Sources	I/O Pins	Voltage Range (Volts)	Number of Instructions	Packages
PIC17C42	25	2K	—	232		TMR0,TMR1, TMR2,TMR3	2	2	Yes	—	Yes	11	33	4.5-5.5	55	40-pin DIP; 44-pin PLCC, MQFP
PIC17C42A	25	2K	—	232		TMR0,TMR1, TMR2,TMR3	2	2	Yes	Yes	Yes	11	33	2.5-6.0	58	40-pin DIP; 44-pin PLCC, TQFP, MQFP
PIC17CR42	25	—	2K	232		TMR0,TMR1, TMR2,TMR3	2	2	Yes	Yes	Yes	11	33	2.5-6.0	58	40-pin DIP; 44-pin PLCC, TQFP, MQFP
PIC17C43	25	4K	—	454		TMR0,TMR1, TMR2,TMR3	2	2	Yes	Yes	Yes	11	33	2.5-6.0	58	40-pin DIP; 44-pin PLCC, TQFP, MQFP
PIC17CR43	25	—	4K	454		TMR0,TMR1, TMR2,TMR3	2	2	Yes	Yes	Yes	11	33	2.5-6.0	58	40-pin DIP; 44-pin PLCC, TQFP, MQFP
PIC17C44	25	8K		454		TMR0,TMR1, TMR2,TMR3	2	2	Yes	Yes	Yes	11	33	2.5-6.0	58	40-pin DIP; 44-pin PLCC, TQFP, MQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.

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PIC17C4X Product Identification System

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.

PART NO. – XX X /XX XXX

Pattern:	QTP, SQTP, ROM Code (factory specified) or Special Requirements. Blank for OTP and Windowed devices	
Package:	P	= PDIP
	JW	= Windowed CERDIP
	P	= PDIP (600 mil)
	PQ	= MQFP
	PT	= TQFP
	L	= PLCC
Temperature Range:	–	= 0˚C to +70˚C
	I	= –40˚C to +85˚C
Frequency Range:	08	= 8 MHz
	16	= 16 MHz
	25	= 25 Mhz
	33	= 33 Mhz
Device:	PIC17C44	: Standard Vdd range
	PIC17C44T	: (Tape and Reel)
	PIC17LC44	: Extended Vdd range

Examples

a) PIC17C42 – 16/P Commercial Temp., PDIP package, 16 MHZ, normal V_{DD} limits

b) PIC17LC44 – 08/PT Commercial Temp., TQFP package, 8MHz, extended V_{DD} limits

c) PIC17C43 – 25I/P Industrial Temp., PDIP package, 25 MHz, normal V_{DD} limits

Sales and Support

Products supported by a preliminary Data Sheet may possibly have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office (see below)
2. The Microchip Corporate Literature Center U.S. FAX: (602) 786-7277
3. The Microchip's Bulletin Board, via your local CompuServe number (CompuServe membership NOT required).

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.
For latest version information and upgrade kits for Microchip Development Tools, please call 1-800-755-2345 or 1-602-786-7302.

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